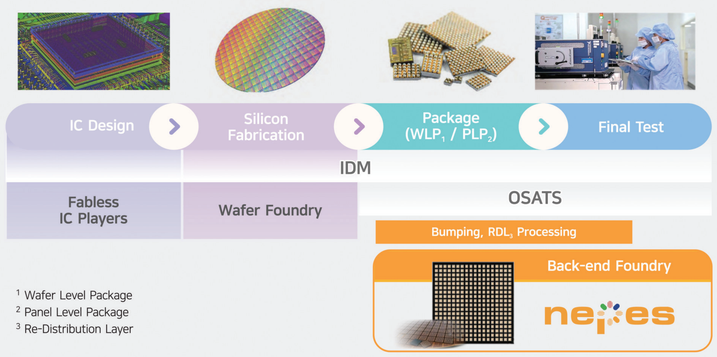
nepes

nepes, Leading Businesses into the Future through hyper-connective technologies

Who we are

nepes' advanced semiconductor technologies including FOPLP and nSiP changes global supply chain

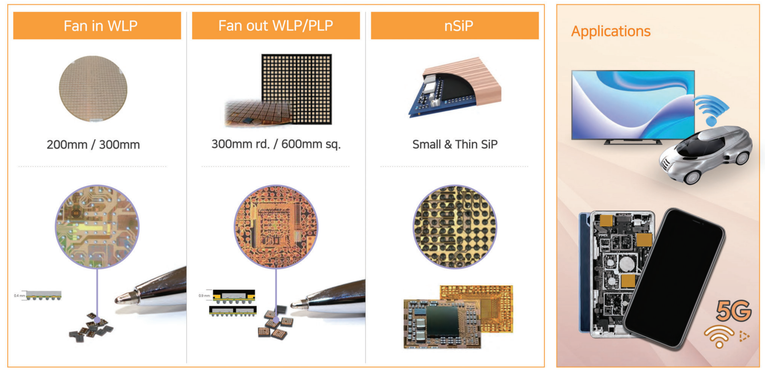
Semiconductor Supply Chain



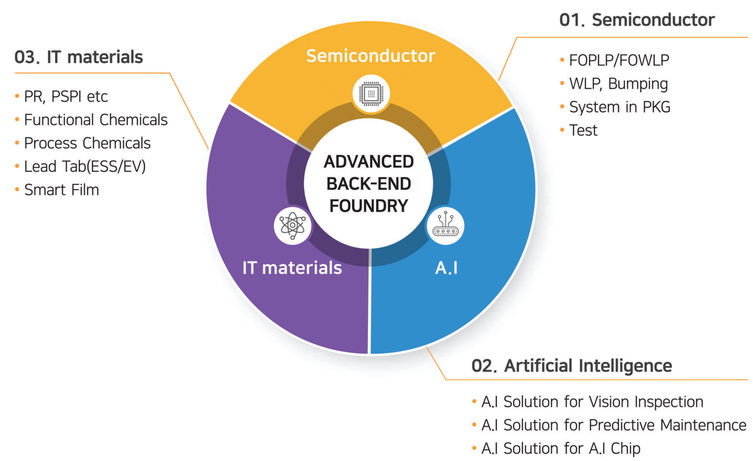
[1] Wafer Level Package
[2] Panel Level Package
[3] Re-Distribution Layer

Core technology

Fan in WLP	Fan out WLP/PLP	nSiP
200mm / 300mm	300mm rd. / 600mm sq.	Small & Thin SiP



Business portfolio



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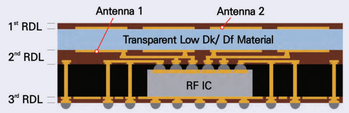
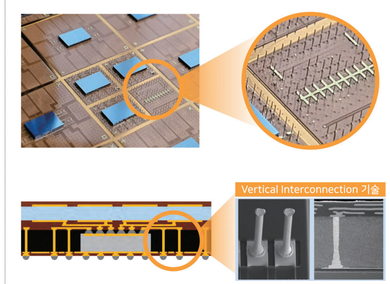
nepes AiP

1. **High RF performance**
   - Minimal signal loss by RDL
   - Small antenna fabrication tolerance by transparent low Dk/ Df material
2. **Small form factor**
   - Reduce package thickness
3. **Design flexibility**
   - Possible easy upscale the AiP with array antenna & multiple chips

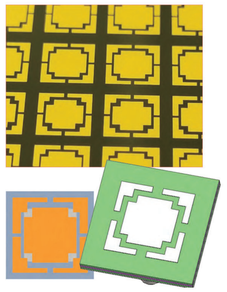


Core technology

Core technology



mmWave Antenna Design



Applications

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